

## Direct Liquid Systems (DL) Assemblies

Stock Locator



Direct-Liquid assemblies are used to cool or heat either objects attached directly to the cold plate, or enclosures by attaching a thermal conductive container to the cold plate. Heat is dissipated to a liquid on the warm side. The liquid circuit is normally of a recirculating type with a pump and a liquid-to-air heat exchanger removing the heat into the ambient air. By using an efficient heat exchanger and one or more DL-assemblies a very powerful yet compact system is created.

Our standard assemblies are optimized for high cooling capacity and efficiency rather than maximum Delta T. Typical applications include temperature cycling of electronic components, laser cooling and analytical instruments.

Specifications apply to warm side Liquid temperature 32°C and nominal Voltage. Tolerances ±10%

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Item #	Max. Cooling Power Pc	Current	Input Power	Max. Ambient Temperature	Lw	Ww
DL-060-12-00	59 watts	4.2 A	50 watts	63 °C	100 mm	60 mm
DL-120-24-00	122 watts	4.2 A	101 watts	62 °C	140 mm	60 mm
DL-210-24-00	207 watts	8.1 A	194 watts	62 °C	240 mm	60 mm

Results 1 - 3 of 3